

IMPEDANCE TABLE

IMPEDANCE	TYPE	LAYER	REF	WIDTH (MM)	SPACE (MM)
50	COPLANAR	F	IN3	0.5144	0.135
50	SE	F/B	IN1/IN2	0.1184	
90	DP	F	IN2	0.1034	0.12


BOARD CHARACTERISTICS

Copper Layer Count:	4	Board Thickness:	0.9732 mm
Board overall dimensions:	45.48 mm x 19.56 mm		
Min track/spacing:	0.1020 mm / 0.1000 mm	Min hole diameter:	0.2500 mm
Copper Finish:	None	Impedance Control:	Yes
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		

Stackup (JLC04101H-1080)

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	White	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.01 mm	Blue	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric 1	prepreg	1080	0.0764 mm	FR4 natural	3.91	0
In1.Cu	copper		0.0152 mm		1	0
Dielectric 2	core	FR4	0.7 mm	Not specified	4.6	0.02
In2.Cu	copper		0.0152 mm		1	0
Dielectric 3	prepreg	1080	0.0764 mm	FR4 natural	3.91	0
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Blue	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	White	1	0

Designed by:
Brendan Bleker



Sheet: Black And White TOP
File: stm32_bluet_pill.kicad_pcb

Title: **stm32_bluet_pill**

Size: A3Date: 2024-04-03KiCad E.D.A. 8.0.6

Rev: **V2**
Id: 1/1

